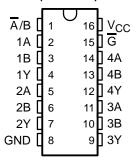
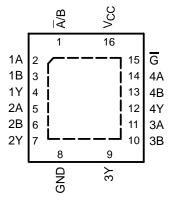
SCLS345I - MAY 1996 - REVISED JULY 2003

- Operating Range 2-V to 5.5-V V_{CC}
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

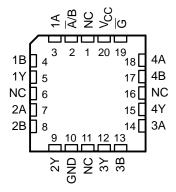
SN54AHC157 . . . J OR W PACKAGE SN74AHC157 . . . D, DB, DGV, N, NS, OR PW PACKAGE (TOP VIEW)



SN74AHC157...RGY PACKAGE (TOP VIEW)



SN54AHC157 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

These quadruple 2-line to 1-line data selectors/multiplexers are designed for 2-V to 5.5-V V_{CC} operation.

The 'AHC157 devices feature a common strobe (\overline{G}) input. When the strobe is high, all outputs are low. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. The devices provide true data.

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Tape and reel	SN74AHC157RGYR	HA157
	PDIP – N	Tube	SN74AHC157N	SN74AHC157N
	SOIC - D	Tube	SN74AHC157D	AHC157
	3010 - 15	Tape and reel	SN74AHC157DR	Ancisi
–40°C to 85°C	SOP – NS	Tape and reel	SN74AHC157NSR	AHC157
	SSOP – DB	Tape and reel	SN74AHC157DBR	HA157
	TSSOP – PW	Tube	SN74AHC157PW	HA157
	1330F = FW	Tape and reel	SN74AHC157PWR	TIATO
	TVSOP – DGV	Tape and reel	SN74AHC157DGVR	HA157
	CDIP – J	Tube	SNJ54AHC157J	SNJ54AHC157J
–55°C to 125°C	CFP – W	Tube	SNJ54AHC157W	SNJ54AHC157W
	LCCC – FK	Tube	SNJ54AHC157FK	SNJ54AHC157FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SCLS345I - MAY 1996 - REVISED JULY 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Output voltage range, V _O (see Note 1)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	73°C/W
(see Note 2): DB package	82°C/W
(see Note 2): DGV package	120°C/W
(see Note 2): N package	67°C/W
(see Note 2): NS package	64°C/W
(see Note 2): PW package	108°C/W
(see Note 3): RGY package	39°C/W
Storage temperature range, T _{Stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The package thermal impedance is calculated in accordance with JESD 51-7.
- 3. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 4)

			SN54A	HC157	SN74A	HC157	UNIT	
			MIN	MAX	MIN	MAX	I UNII	
Vcc	Supply voltage		2	5.5	2	5.5	V	
		V _{CC} = 2 V	1.5		1.5			
V_{IH}	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V	
		V _{CC} = 5.5 V	3.85		3.85		1	
		V _{CC} = 2 V		0.5		0.5		
V_{IL}	Low-level input voltage	V _{CC} = 3 V		0.9		0.9	V	
		V _{CC} = 5.5 V		1.65		1.65		
٧ı	Input voltage	•	0	5.5	0	5.5	V	
٧o	Output voltage		0	Vcc	0	Vcc	V	
		V _{CC} = 2 V		- 50		-50	μΑ	
ЮН	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4		-4	A	
		$V_{CC} = 5 V \pm 0.5 V$		-8		-8	mA	
		V _{CC} = 2 V		50		50	μА	
loL	Low-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		4		4	^	
		$V_{CC} = 5 V \pm 0.5 V$		8		8	mA	
A+/A>/	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100		100	ns/V	
Δt/Δv	Input transition rise or fall rate $\frac{V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}}{V_{CC}}$			20		20	115/V	
TA	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCLS345I - MAY 1996 - REVISED JULY 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETED	TEST COMPITIONS	V	T,	\ = 25°C	;	SN54AHC157		SN74AHC157		UNIT	
PARAMETER		TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
			2 V	1.9	2		1.9		1.9			
		I _{OH} = -50 μA	3 V	2.9	3		2.9		2.9			
VOH			4.5 V	4.4	4.5		4.4		4.4		V	
		I _{OH} = -4 mA	3 V	2.58			2.48		2.48			
		I _{OH} = -8 mA	4.5 V	3.94			3.8		3.8			
			2 V			0.1		0.1		0.1		
		I _{OL} = 50 μA	3 V			0.1		0.1		0.1	1	
VOL			4.5 V			0.1		0.1		0.1	V	
		I _{OL} = 4 mA	3 V			0.36		0.5		0.44		
		I _{OL} = 8 mA	4.5 V			0.36		0.5		0.44		
lı	A or B inputs	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1*		±1	μΑ	
ICC	_	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40		40	μА	
Ci		V _I = V _{CC} or GND	5 V		2	10				10	pF	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0 \text{ V}$.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	Δ = 25°(C	SN54A	HC157	SN74AI	HC157	UNIT					
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT					
tPLH	A or B	Υ	C: = 15 pE		6.2**	9.7**	1**	11.5**	1	11.5	ns					
^t PHL	AUB	Y $C_L = 15 pF$	C[= 15 pr		6.2**	9.7**	1**	11.5**	1	11.5	115					
^t PLH	Ā/B	Y	C _L = 15 pF		8.4**	13.2**	1**	15.5**	1	15.5	ns					
^t PHL	A/B	•	CL = 15 pr		8.4**	13.2**	1**	15.5**	1	15.5	115					
^t PLH	Ю	Y	C _I = 15 pF		8.7**	13.6**	1**	16**	1	16	ns					
^t PHL	g	'	OL = 13 pi		8.7**	13.6**	1**	16**	1	16	113					
^t PLH	A or B	Y	C: - 50 pF		8.7	13.2	1	15	1	15	ns					
^t PHL	AUB	ī	C _L = 50 pF		8.7	13.2	1	15	1	15	115					
^t PLH	Ā/B	Υ	C ₁ = 50 pF		10.9	16.7	1	19	1	19	ns					
^t PHL	A/B	Y	Y	ľ	CL = 50 pr	CL = 50 pr	CL = 30 pr	OL = 30 pr		10.9	16.7	1	19	1	19	115
^t PLH	IG	Y	Ct = 50 pF		11.2	17.1	1	19.5	1	19.5	ns					
t _{PHL}	G	ſ	C _L = 50 pF		11.2	17.1	1	19.5	1	19.5	115					

^{**} On products compliant to MIL-PRF-38535, this parameter is not production tested.

SCLS345I - MAY 1996 - REVISED JULY 2003

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	Վ = 25° C	;	SN54A	HC157	SN74A	HC157	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	A or B	Y	C _I = 15 pF		4.1*	6.4*	1*	7.5*	1	7.5	ns
^t PHL	AOIB	ı	C[= 15 pr		4.1*	6.4*	1*	7.5*	1	7.5	115
^t PLH	Ā/B	Y	C 15 pE		5.3*	8.1*	1*	9.5*	1	9.5	ns
t _{PHL}	A/B	T	C _L = 15 pF		5.3*	8.1*	1*	9.5*	1	9.5	110
tPLH	ĪG	Y	C _I = 15 pF		5.6*	8.6*	1*	10*	1	10	20
^t PHL	G	T	CL = 15 pr		5.6*	8.6*	1*	10*	1	10	ns
t _{PLH}	A or B	Y	C _I = 50 pF		5.6	8.4	1	9.5	1	9.5	ns
^t PHL	AUB	T	CL = 50 pr		5.6	8.4	1	9.5	1	9.5	110
^t PLH		Y	C 50 pF		6.8	10.1	1	11.5	1	11.5	ns
^t PLH	A/B	T	C _L = 50 pF		6.8	10.1	1	11.5	1	11.5	110
^t PLH	G	Υ	C ₁ = 50 pF		7.1	10.6	1	12	1	12	ns
tPHL	G	'	CL = 50 pr		7.1	10.6	1	12	1	12	115

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 5)

	DADAMETED	SN7	UNIT		
	PARAMETER		TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}			0.8	V
V _{OL(V)}	Quiet output, minimum dynamic VOL			-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		4.8		V
VIH(D)	High-level dynamic input voltage	3.5			V
V _{IL(D)}	Low-level dynamic input voltage			1.5	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
I	C _{pd} Power dissipation capacitance	No load,	f = 1 MHz	11	pF





.com 19-May-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9764201Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9764201QEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
5962-9764201QFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SN74AHC157D	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHC157DBLE	OBSOLETE	SSOP	DB	16		TBD	Call TI	Call TI
SN74AHC157DBR	ACTIVE	SSOP	DB	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74AHC157DBRE4	ACTIVE	SSOP	DB	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHC157DGVR	ACTIVE	TVSOP	DGV	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHC157DGVRE4	ACTIVE	TVSOP	DGV	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHC157DR	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74AHC157N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74AHC157NSR	ACTIVE	so	NS	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR Level-1-235C-UNLIM
SN74AHC157PW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHC157PWLE	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI
SN74AHC157PWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHC157RGYR	ACTIVE	QFN	RGY	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SNJ54AHC157FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHC157J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54AHC157W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

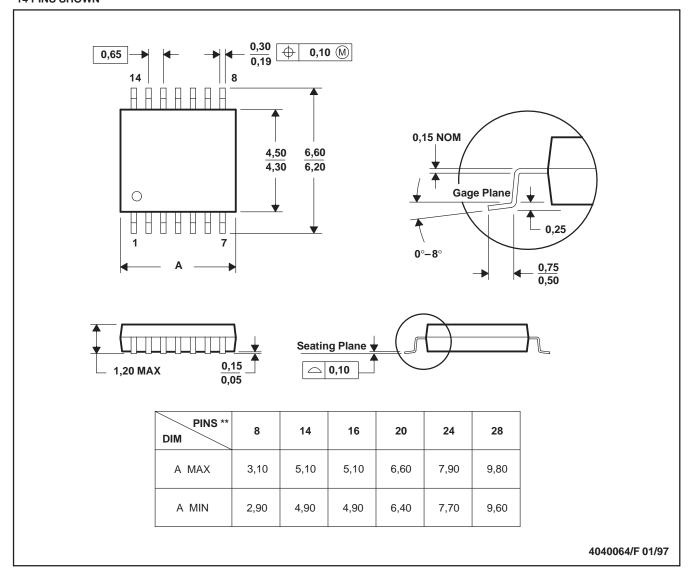
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated